

a system requiring an operator and, at this time when recruitment and retention of staff is proving to be so difficult, the AOI Island offers manufacturers a cost-effective solution.

The AOI Island is fed from one direction; simply take a magazine of PCBs to the loader/unloader and push the start button. The boards load and unload into the AOI from the same side, and after inspection they are sorted into either good or no-good magazines, allowing the good boards to be removed and continue the production process, whilst the failed boards can be taken to the remote repair area.



The AOI system is the multi award-winning Mirtec MV-6 Omni 3D Inspection system, which is recognised as having the best cameras, 3D sensors, Z-axis and double-sided inspection capability available, as well as a lighting array combined with automatic programming and debug software to provide unparalleled inspection quality.

“We have more than 140 Mirtec installations within our marketplace, and many of our customers are looking for a more automated solution due to the labour issues that do not seem to be improving any time soon,” said David Bennett, Managing Director of Bentec Ltd. “We developed the AOI Island and, with so many wanting to see it for themselves, it became obvious we needed one at our demonstration facility. There will always be customers who choose the benchtop solution that Mirtec leads the world in, but as both the inline and benchtop are identical in specification, we can offer the best solution that suits our customers’ needs.”

www.Bentec-Int.com



CORTEC® PRESENTS LATEST PACKAGING INNOVATION: CORSHIELD® RESEALABLE BUBBLE BAGS POWERED BY NANO-VPCI®!

CorShield® Resealable Bubble Bags and Static Shielding Bubble Bags combine volatile corrosion inhibitors with cushioning packing bubbles to provide protection for sensitive or delicate components. The air filled bubbles offer superior protection and burst strength, withstanding high pressure and abuse and have air retention properties. This will ensure that bubbles stay inflated and provide long-lasting performance.

Bubble bags are ideal for use where the item requires both mechanical and corrosion protection. They are excellent for protecting high precision metals from damaging, scratching and corrosion while in transit or storage. Bags can be used for shipping and storage of various metal components. These recyclable and therefore environmentally safe bags are developed in Croatian EcoCortec® plant, European daughter company of Cortec® Corporation. They are produced in their manufacturing facility. CorShield® Bubble Bags are now readily available for their customers.



Multimetal Protection

Using Vapor phase Corrosion Inhibitor (VpCI®) technology, the bubbles protect a variety of metals, including carbon steel, aluminum, copper, brass, silver and stainless steels, without leaving film or residue on packaged items. CorShield® Bubble Bags are non-toxic and recyclable. Components that need protection are placed in the bags and in matter of hours, the vapor from the VpCI® bubbles saturates the enclosed airspace. The VpCI® vapor migrates through the air to reach all exposed metal surfaces. The VpCI's then condense, forming a thin, protective layer. CorShield® VpCI Bubble Bags are designed for cushioning and surface protection applications.

FEATURES

- Simple, safe to use.
- Provide a unique combination of cushioning and corrosion protection
- Multimetal protection through Vapor phase Corrosion Inhibitor (VpCI) technology
- VpCI vapor does not interfere with subsequent processing (painting, welding, cleaning, soldering, etc.)
- No adverse effects on plastic (lexane), optics, elastomers and other non-metals
- Complete product protection during storage as well as during domestic and overseas shipments, eliminating any rust claims.

The product meets NACE TM0208-2018 standard for corrosion protection as well as German TL-8135-002 standards for corrosion protection.

www.cortecvci.com



INDIUM CORPORATION EARNS BISINFOTECH BETA AWARD

Indium Corporation has earned a BISinfotech BETA Award as Global Leader in Solder and Materials category. The honor was presented during a live streaming of the awards ceremony on Wednesday, November 30. This marks the third consecutive year Indium Corporation has received a BETA Award.

The annual BETA Awards, presented by Indian technology magazine BISinfotech, recognize outstanding contributions and innovations from India's top technology enablers. The prestigious award brings together the leading personalities and organizations from across the country's technology sector who are helping the industry achieve new milestones.

“At Indium Corporation, we believe that materials science can change the world,” said Tim Twining, Vice President of Sales, Marketing, and Technical Service. “We are honored to receive the BISinfotech BETA Award as Global Leader in Solder and Materials as it provides further proof that our innovative products are continuing to make a global impact on the industry.”

Indium Corporation continues to deliver an ever-growing suite of innovative solder and thermal materials designed to enable world-changing technologies from the 5G lifestyle to electric vehicles, mobile communications, and more. Since its founding, Indium Corporation has been driven by its curiosity to look at materials from a different perspective—transforming the ordinary into the unexpected.

www.indium.com



ITW EAE INTRODUCES AUTO EXIT WING FEATURE FOR ELECTROVERT® WAVE SOLDERING MACHINES

ITW EAE is releasing a new feature for the Electrovert Wave Soldering machines that provides automatic adjustment of the laminar wave flow to match the board velocity. To fully optimize the flow dynamics of the laminar wave, the velocity of the PCB needs to equal the flow of the solder over the weir of the exit wing. When the wave flow is fully optimized, the PCB ‘peels’ away from the solder which minimizes the opportunity for bridging defects to occur.

Electrovert's Auto Exit Wing provides highly repeatable, precisely controlled exit wing adjustment that has been proven to deliver up to a 70% reduction in bridging defects and